

Radiation Hardened Dual D Flip Flop

with **DICE** latches and **cold sparing**

1 GENERAL DESCRIPTION

The **AF54RHC705** is a radiation-hardened by design **dual D flip flop** that is ideally suited for space, medical imaging and other applications demanding radiation tolerance and high reliability. It is fabricated in a 180 nm CMOS process utilizing proprietary radiation-hardening techniques, delivering high resiliency to single-event effects (SEE) and to a total ionizing dose (TID) to 300 krad (Si).

This device is a member of the Apogee Semiconductor **AF54RHC logic family** operating across a voltage supply range of **1.65 V to 5.5 V**.

This device consists of two D flip-flops with individual clear and clock inputs. Information at a D input is transferred to the corresponding Q output on the next positive-going edge of the clock input. Both Q and \bar{Q} outputs are available for each flip-flop. The clear input is asynchronous.

Zero-power penalty™ cold-sparing is supported, along with Class 2 ESD protection on all inputs and outputs. A proprietary output stage and robust power-on reset (POR) circuit allow the AF54RHC705 to be cold-sparged in any redundant configuration with no static power loss on any pad of the device. The redundant output stage also features a high drive capability with low static power loss.

The AF54RHC705 is dual radiation hardened D Flip Flop capable of being clocked up to 100MHz at 3.3V. This device contains latches based on the Dual Interlocked storage Cells (DICE) that are tolerant to Single Event Upsets.

The AF54RHC705 also features a triple-redundant design throughout its entire circuitry, which allows it to be immune to single-event transients (SET) without requiring additional redundant devices.

Ordering information may be found in Table 11 on Page 13.

1.1 FEATURES

- **1.65 VDC to 5.5 VDC** operation
- Extended operating temperature range (-55 °C to +125 °C)
- Inputs tolerant up to 5.5 V DC at any V_{CC}
- Tri-state output drivers
- Proprietary **cold-sparing capability** with **zero static power penalty**
- **Built-in triple redundancy** for enhanced reliability
- Internal power-on reset (POR) circuitry ensures reliable power up and power down responses during hot plug and cold sparing operations
- Class 2 ESD protection (4000 V HBM, 500 V CDM)
- TID resilience of **300 krad (Si)**
- SEL immune to LET of **80 MeV-cm²/mg**

1.2 LOGIC DIAGRAM

The AF54RHC705 block diagram is shown below:

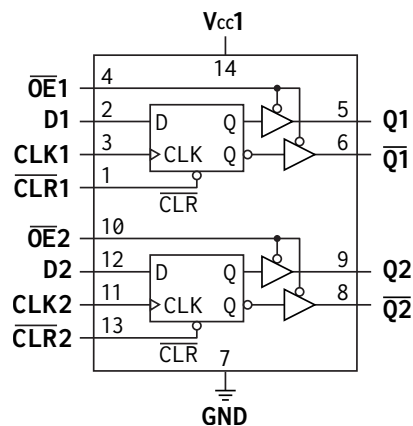


Figure 1: AF54RHC705 block diagram

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2 ACRONYMS AND ABBREVIATIONS

ESD	Electrostatic Discharge
POR	Power On Reset
RHA	Radiation Hardness Assurance
SEE	Single Event Effects
SEL	Single Event Latchup
SET	Single Event Transient
TID	Total Ionizing Dose
TMR	Triple Modular Redundancy
CDM	Charged-device Model
HBM	Human-body Model

3 LOGIC DATA

3.1 TRUTH TABLE

The AF54RHC705 truth table is found in Table 1. **H** indicates HIGH logic level, **L** indicates LOW logic level, and **X** indicates DON'T CARE for each flip-flop. **Q_{INT}** is stored value in device.

Input				Internal FF	Output	
\overline{OE}	\overline{CLR}	CLK	D	Q _{INT}	Q	\overline{Q}
H	L	X	X	L	Z	Z
H	H	↑	H	H	Z	Z
H	H	↑	L	L	Z	Z
H	H	H, L or ↓	X	No Change	Z	Z
L	L	X	X	L	Q _{INT}	$\overline{Q_{INT}}$
L	H	↑	H	H	Q _{INT}	$\overline{Q_{INT}}$
L	H	↑	L	L	Q _{INT}	$\overline{Q_{INT}}$
L	H	H, L or ↓	X	No Change	Q _{INT}	$\overline{Q_{INT}}$

Table 1: AF54RHC705 device truth table (per gate).

4 PIN CONFIGURATION

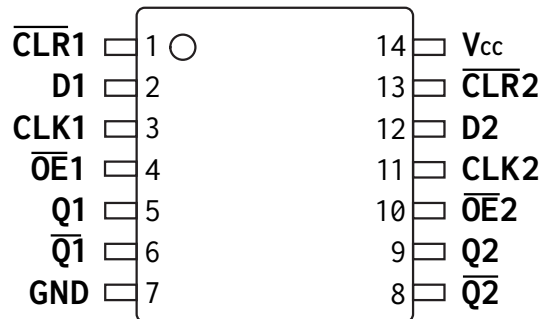


Figure 2: AF54RHC705 Device Pinout.

Table 2: AF54RHC705 device pinout description

PIN NAME(S)	PIN NUMBER(S)	DESCRIPTION
$\overline{CLR1}$, $\overline{CLR2}$	1, 13	Asynchronous Clears
D1, D2	2, 12	Data Inputs
Q1, Q2	5, 9	Outputs
$\overline{Q1}$, $\overline{Q2}$	6, 8	Complement Outputs
$\overline{OE1}$, $\overline{OE2}$	4, 10	Output Enables
V _{CC}	14	Positive Voltage Supply
GND	7	Ground

5 ELECTRICAL CHARACTERISTICS

The sign convention for current follows JEDEC standards with negative values representing current sourced from the device and positive values representing current sunk into the device.

5.1 ABSOLUTE MAXIMUM RATINGS

Excursions beyond the values listed in Table 3 may cause permanent damage to the device. Proper function of the device cannot be guaranteed if these values are exceeded, and long-term device reliability may be affected. Functionality of the device at these values, or beyond those listed in [Recommended Operating Conditions](#) (Table 4) is not guaranteed.

All parameters are specified across the entire operating temperature range unless otherwise specified.

Table 3: Absolute Maximum Ratings

SYMBOL	PARAMETER		VALUE	UNITS
V_{CC}	Supply Voltage		-0.5 to +5.5	V
V_I	Input voltage range		-0.5 to +5.5	V
V_O	Output voltage range		-0.5 to $V_{CC} + 0.5$ ⁽¹⁾	V
$I_{IK} (V_I < 0)$	Input clamp current		100	mA
I_O	Continuous output current (per pin)		100	mA
I_{CC}	Maximum supply current		100	mA
V_{ESD}	ESD Voltage	HBM	4000	V
		CDM	500	V
T_J	Operating junction temperature range		-55 to +150	°C
T_{STG}	Storage temperature range		-65 to +150	°C

⁽¹⁾ V_O must remain below absolute maximum rating of V_{CC}

5.2 RECOMMENDED OPERATING CONDITIONS

All recommended parameters below are specified across the entire operating temperature range unless otherwise specified.

Table 4: Recommended Operating Conditions

SYMBOL	PARAMETER		MIN	MAX	UNITS
V_{CC}	Supply voltage		1.65	5.5	V
V_I	Input voltage range		0	5.5	V
V_O	Output voltage range		0	V_{CC}	V
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$	1.4	-	V
		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$	1.9	-	
		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	2.5	-	
		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$	3.8	-	
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$	-	0.4	V
		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$	-	0.6	
		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	-	0.9	
		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$	-	1.35	
I_{OH}	HIGH-level output current	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$	-	-4	mA
		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$	-	-8	
		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	-	-16	
		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$	-	-24	
I_{OL}	LOW-level output current	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$	-	4	mA
		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$	-	8	
		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	-	16	
		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$	-	24	
t_r, t_f	Input rise or fall time (10% - 90%)	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$	-	1000	ns
		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$	-	600	
		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	-	500	
		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$	-	400	

Table 5: Thermal Information

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
T_J	Operating junction temperature	-55	-	+125	°C
$R_{\theta JA}$	Junction to ambient thermal resistance	-	100	-	°C/W

5.3 STATIC CHARACTERISTICS

All parameters are specified across the entire operating temperature range unless otherwise specified.

Table 6: DC Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	V _{CC}	MIN	TYP	MAX	UNITS
V _{OL}	LOW-level output voltage	I _O = 100 μA	1.65 to 5.5 V	-	0.02	0.05	V
		I _O = 1 mA	1.65 to 5.5 V	-	0.05	0.15	V
		I _O = 4 mA	1.65 V	-	0.29	0.65	V
			2.3 V	-	0.3	0.6	V
			3.0 V	-	0.2	0.4	V
			4.5 V	-	0.2	0.4	V
		I _O = 8 mA	2.3 V	-	0.6	1.0	V
			3.0 V	-	0.4	0.8	V
			4.5 V	-	0.3	0.6	V
		I _O = 16 mA	3.0 V	-	1.0	1.4	V
			4.5 V	-	1.1	1.2	V
		I _O = 24 mA	4.5 V	-	1.1	1.5	V
V _{OH}	HIGH-level output voltage	I _O = -100 μA	1.65 to 5.5 V	V _{CC} - 0.1	V _{CC} - 0.02	-	V
		I _O = -1 mA	1.65 to 5.5 V	V _{CC} - 0.15	V _{CC} - 0.08	-	V
		I _O = -4 mA	1.65 V	1	1.35	-	V
			2.3 V	1.8	2.0	-	V
			3.0 V	2.6	2.7	-	V
			4.5 V	4.2	4.4	-	V
		I _O = -8 mA	2.3 V	1.4	1.7	-	V
			3.0 V	2.2	2.5	-	V
			4.5 V	3.9	4.1	-	V
		I _O = -16 mA	3.0 V	1.5	2.0	-	V
			4.5 V	3.3	3.8	-	V
		I _O = -24 mA	4.5 V	3.0	3.5	-	V
I _{CC}	Quiescent supply current	V _I = V _{CC} or GND I _O = 0 mA	5.5 V	-	TBD	TBD	μA
I _I	Input current	V _I = V _{CC} or GND	1.65 to 5.5 V	-	-	±1	μA
I _{OFF}	Powerdown leakage current ⁽¹⁾	V _I = V _{CC} or GND	OFF ⁽²⁾	-	-	5	μA

⁽¹⁾ into any input or output port

⁽²⁾ V_{CC} is disconnected or at GND potential

5.4 DYNAMIC CHARACTERISTICS

All parameters are specified across the entire operating temperature range unless otherwise specified.

5.4.1 Timing Requirements

Table 7: Timing Requirements

SYMBOL	PARAMETER	CONDITIONS	V _{CC}	MIN	TYP	MAX	UNITS
t_{su}	Setup time (data to clock)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	-	ns
			3.0 to 3.6 V	-	TBD	-	ns
			2.3 to 2.7 V	-	TBD	-	ns
			1.65 to 1.95 V	-	TBD	-	ns
t_h	Hold Time (clock to data Q, \bar{Q})	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	-	ns
			3.0 to 3.6 V	-	TBD	-	ns
			2.3 to 2.7 V	-	TBD	-	ns
			1.65 to 1.95 V	-	TBD	-	ns
t_w	Pulse Width (Clock)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	-	ns
			3.0 to 3.6 V	-	TBD	-	ns
			2.3 to 2.7 V	-	TBD	-	ns
			1.65 to 1.95 V	-	TBD	-	ns
f_{max}	Clock Frequency (50% Duty Cycle)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	-	100	MHz
			3.0 to 3.6 V	-	-	100	MHz
			2.3 to 2.7 V	-	-	10	MHz
			1.65 to 1.95 V	-	-	10	MHz

5.4.2 Operating Characteristics

Table 8: Operating Characteristics

SYMBOL	PARAMETER	CONDITIONS	V _{CC}	MIN	TYP	MAX	UNITS
C_{in}	Input capacitance	$V_I = V_{CC} \text{ or GND}$	1.65 to 5.5 V	-	6	10	pF
C_{pd}	Power dissipation capacitance	$I_O = 0 \text{ mA}, f = 1 \text{ MHz}$	5.5 V	-	40	-	pF

5.4.3 Switching Characteristics

Table 9: Switching Characteristics

SYMBOL	PARAMETER	CONDITIONS	V _{CC}	MIN	TYP	MAX	UNITS
t_{pdclk}	Propagation delay (Clock to data Q , $\overline{\mathbf{Q}}$)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	TBD	ns
			3.0 to 3.6 V	-	TBD	TBD	ns
			2.3 to 2.7 V	-	TBD	TBD	ns
			1.65 to 1.95 V	-	TBD	TBD	ns
t_{pdclr}	Propagation delay ($\overline{\text{CLR}}$ to Q , $\overline{\mathbf{Q}}$)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	TBD	ns
			3.0 to 3.6 V	-	TBD	TBD	ns
			2.3 to 2.7 V	-	TBD	TBD	ns
			1.65 to 1.95 V	-	TBD	TBD	ns
t_{clr}	Pulse width (CLR)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	-	ns
			3.0 to 3.6 V	-	TBD	-	ns
			2.3 to 2.7 V	-	TBD	-	ns
			1.65 to 1.95 V	-	TBD	-	ns
t_{en}	Output enable time ($\overline{\text{OE}}$ ↓ to data Q , $\overline{\mathbf{Q}}$)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	TBD	ns
			3.0 to 3.6 V	-	TBD	TBD	ns
			2.3 to 2.7 V	-	TBD	TBD	ns
			1.65 to 1.95 V	-	TBD	TBD	ns
t_{dis}	Output disable Time ($\overline{\text{OE}}$ ↑ to data Q , $\overline{\mathbf{Q}}$)	$C_L = 50 \text{ pF}$	4.5 to 5.5 V	-	TBD	TBD	ns
			3.0 to 3.6 V	-	TBD	TBD	ns
			2.3 to 2.7 V	-	TBD	TBD	ns
			1.65 to 1.95 V	-	TBD	TBD	ns

5.5 RADIATION RESILIENCE

For detailed radiation testing reports, please contact Apogee Semiconductor at sales@apogeesemi.com.

Table 10: Radiation Resilience Characteristics

PARAMETER	CONDITIONS	VALUE	UNITS
Total Ionizing Dose (TID)	Please contact Apogee Semiconductor for test report.	300	krad (Si)
SEE Onset LET Threshold	Please contact Apogee Semiconductor for test report.	≥ 80	MeV-cm ² /mg

5.6 CHARACTERISTICS MEASUREMENT INFORMATION

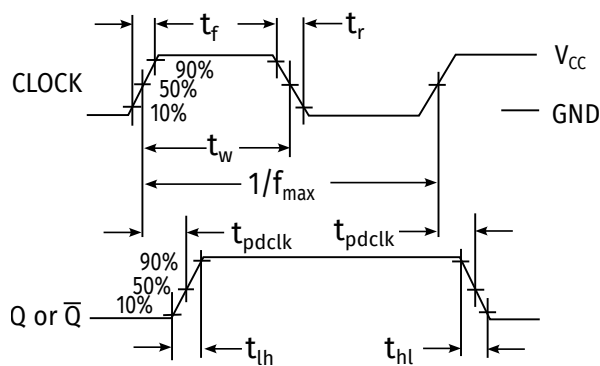


Figure 3: Timing measurements

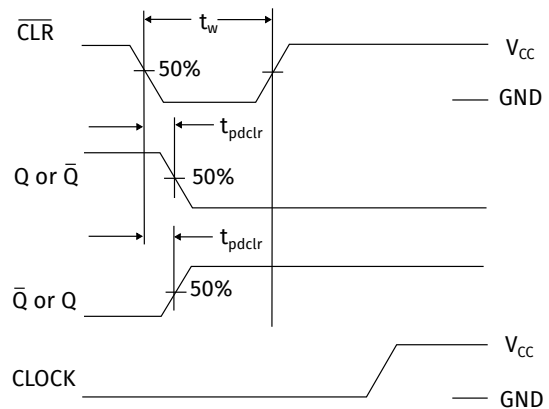


Figure 4: Propagation delay measurement

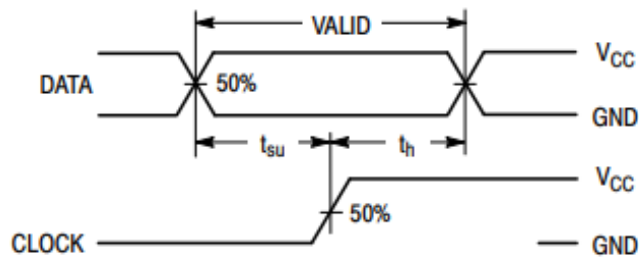


Figure 5: Setup and hold time measurement

6 DETAILED DESCRIPTION

The AF54RHC705 is a dual D flip flop designed to operate from a wide supply voltage of 1.65 to 5.5 V with fully redundant input and output stages, providing for superior radiation resilience.

The output and input stages are constructed with transient activated clamps (Figure 6, 7) that prevent inadvertent biasing of the V_{CC} power rail through parasitic diodes inherent to conventional input, output, and ESD circuits. The IC also incorporates an internal power-on reset (POR) circuit that prevents the output from driving erroneous results during power-on, and guarantees correct operation at power supply voltages as low as 1.65 V. While the supply is ramping, the POR holds the output buffer in tri-state, a feature that prevents unwanted DC current during cold sparing on input and output pins.

The AF54RHC family's I/O protection circuitry allows for cold sparing configurations as it avoids a leakage current penalty on inputs and outputs while in a power-down state. This can result in considerable power savings in systems where multiple-path redundancy is employed. The ESD clamp circuits for this logic family are designed to support Class 2 ESD levels of 4 kV HBM and 500 V CDM.

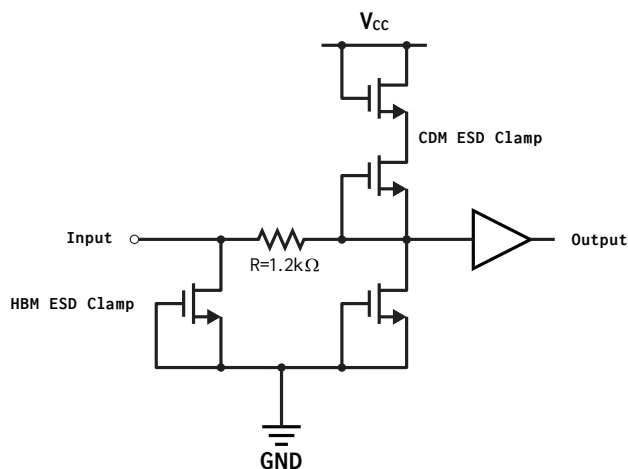


Figure 6: Details of input pin structure

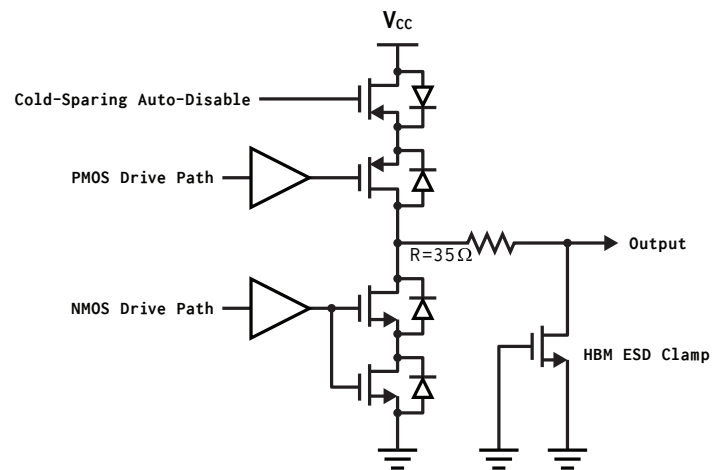


Figure 7: Details of output pin structure

Note

During tri-state, the application must ensure that the output pins are either held or switched to logic high or logic low levels i.e. close to V_{CC} or **GND**, otherwise increased supply current can occur.

7 APPLICATIONS INFORMATION

7.1 USE IN COLD-SPARING CONFIGURATION

As the AF54RHC family is radiation-hardened by design and includes internal TMR, it can be utilized in high-reliability applications without additional supporting circuitry or devices. Nonetheless, some application requirements call for fully-redundant designs, where an “A” and a “B” device are required, often on separate power rails.

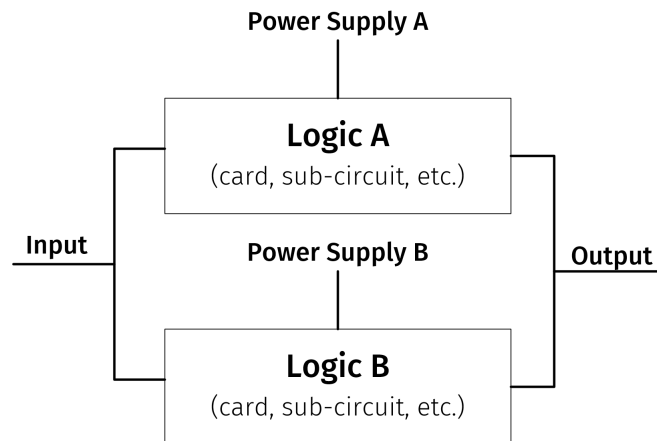


Figure 8: Two-path cold-sparing configuration.

With the cold-sparing capability of the AF54RHC family, fully redundant “A” and “B” functions may be placed in parallel (as seen in Figure 8) running off redundant power supplies. The inputs and outputs on each one of these functions are assumed to be based on the AF54RHC family, allowing for direct parallel connection without unwanted leakage current paths during cold sparing. In the event of a failure in power supply A or within function A, the system can simply shut power supply A off and switch on power supply B, without requiring additional input or output switching or configuration changes.

7.2 POWER SUPPLY RECOMMENDATIONS

This device can operate at any voltage within the range specified in [Table 4 Recommended Operating Conditions](#).

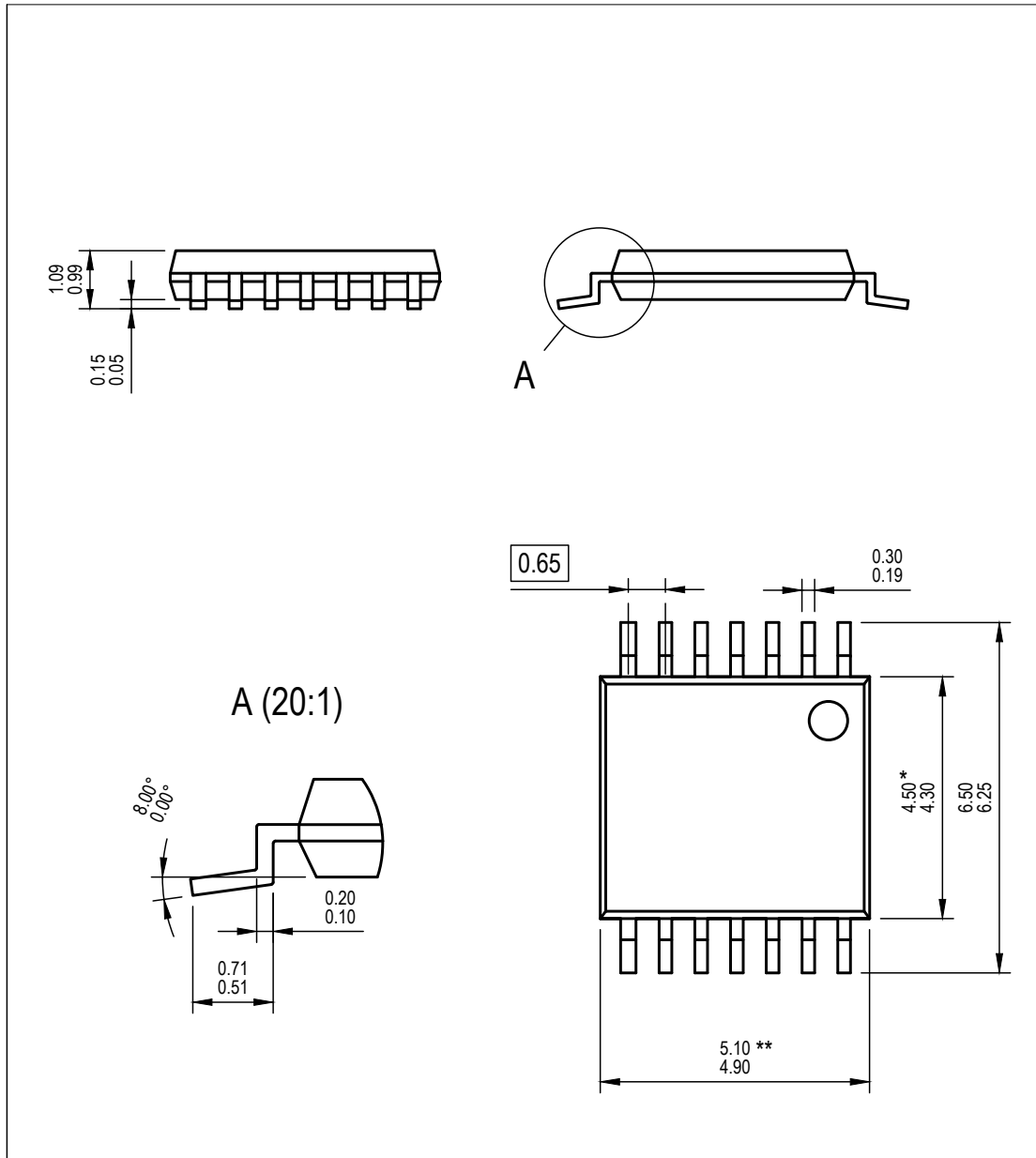
At a minimum, a 16 VDC (or higher), X7R-rated 0.1 μ F ceramic decoupling capacitor should be placed near (within 1 cm) the V_{CC} pin of the device.

7.3 APPLICATION TIPS

Unused **inputs** must **not** be left floating. They may be connected to either a low (GND) or high (V_{CC}) bias to provide a known state at the input of the device. Resistors may be used to tie off unused inputs. In the event of a design change, such resistors can be removed, thereby allowing use of the inputs without having to cut traces on the PCB.

An unused **output** may be left floating. It is suggested that it be routed to a test point or similar accessible structure in case the gate needs to be utilized as part of a design revision.

8 PACKAGING INFORMATION



Notes:

1. All linear dimensions are in millimeters. Dimensioning and tolerancing are as per ISO/TS 128-71:2010
2. The part is compliant with JEDEC MO-153 specifications.

* Body width does **not** include interlead flash. Interlead flash shall not exceed 0.25 mm each side.

** Body length does **not** include mold flash, protrusion, or gate burrs. Mold flash, protrusions, and gate burrs shall not exceed 0.15 mm on each side.

Figure 9: Package Mechanical Detail

9 ORDERING INFORMATION

Example part numbers for the AF54RHC705 are listed in Table 11. The full list of options for this part can be found in Figure 10. Please contact Apogee Semiconductor sales at sales@apogeesemi.com for further information on sampling, lead time and purchasing on specific part numbers.

Table 11: AF54RHC705 Ordering Information

DEVICE	DESCRIPTION	PACKAGE
AF54RHC705ELT-W	Radiation Hardened Dual D Flip Flop (for evaluation only)	Plastic TSSOP-14
AF54RHC705ALT-T	Radiation Hardened Dual D Flip Flop (300 krad (Si))	Plastic TSSOP-14

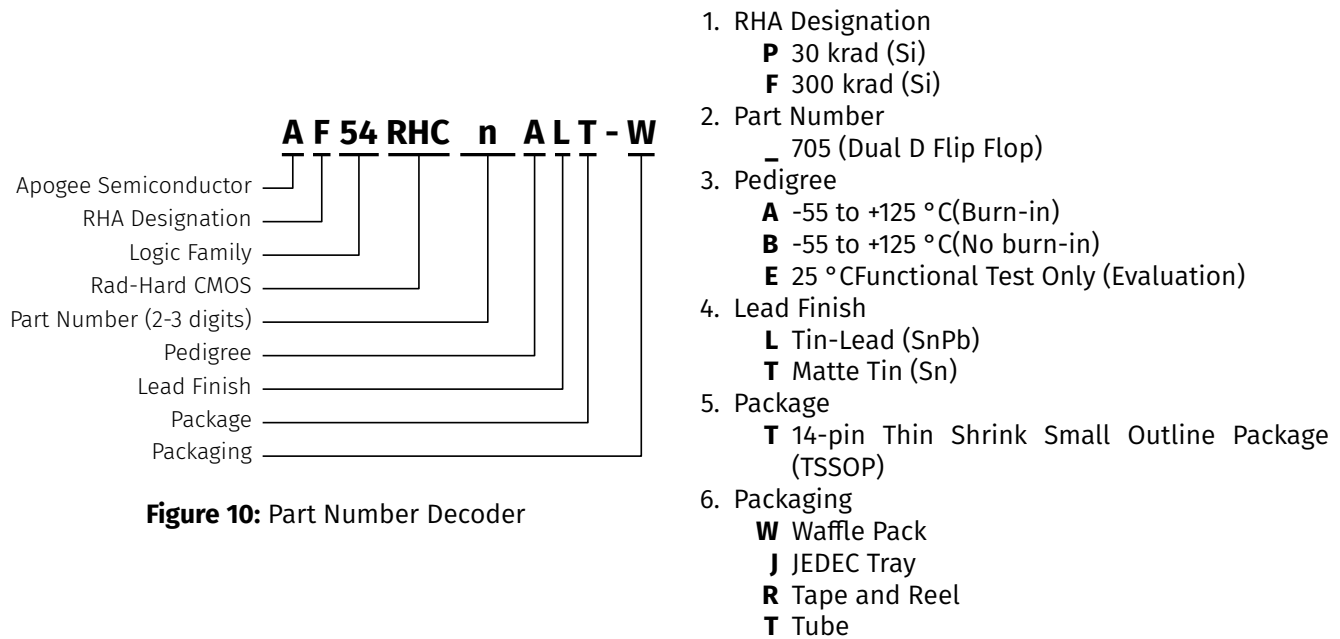


Figure 10: Part Number Decoder

10 REVISION HISTORY

REVISION	DESCRIPTION	DATE
A00	Initial Internal Release.	2024-04-29

For the latest version of this document, please visit <https://www.apogeesemi.com>.

11 LEGAL

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